

Ryo Taguchi

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Nanoscale Analysis of Surface Bending Strain in Film Substrates for Preventing Fracture in Flexible Electronic Devices. <i>Advanced Materials Interfaces</i> , 2021, 8, 2001662.	3.7	20
2	Experimental and theoretical analyses of curvature and surface strain in bent polymer films. <i>Applied Physics Express</i> , 2020, 13, 056502.	2.4	13
3	Quantitative analysis of bending hysteresis by real-time monitoring of curvature in flexible polymeric films. <i>Soft Matter</i> , 2021, 17, 4040-4046.	2.7	7
4	Wideband reflection wavelength tuning by bending of cholesteric liquid crystal elastomer films. <i>Journal of Applied Physics</i> , 2021, 129, .	2.5	6
5	Novel Bending Sensor Based on a Solution-Processed Cu ₂ O Film with High Resolution Covering a Wide Curvature Range. <i>ACS Omega</i> , 2021, 6, 32647-32654.	3.5	5
6	Out-of-plane Strain Measurement of A Silicone Elastomer by means of A Cholesteric Liquid Crystal Sensor. <i>Journal of Photopolymer Science and Technology = [Fotoporima Konwakai Shi]</i> , 2020, 33, 81-84.	0.3	4
7	Neutral Mechanical Plane Shifting in Bending Elastomer Film Revealed by Quantification of Internal Strain. <i>Advanced Engineering Materials</i> , 2022, 24, 2101041.	3.5	3
8	Validation of theoretical analysis of surface bending strain in polymer films by surface-labeled grating method. <i>AIP Advances</i> , 2022, 12, 015324.	1.3	3
9	Invited Paper: Analysis of Dynamic Strain on Foldable Devices. <i>Digest of Technical Papers SID International Symposium</i> , 2020, 51, 417-420.	0.3	1
10	Effect of the Concentration Gradient on Molecular Alignment by Scanning Wave Photopolymerization. <i>Journal of Photopolymer Science and Technology = [Fotoporima Konwakai Shi]</i> , 2020, 33, 291-294.	0.3	1
11	Surface Bending Strain: Nanoscale Analysis of Surface Bending Strain in Film Substrates for Preventing Fracture in Flexible Electronic Devices (<i>Adv. Mater. Interfaces</i> 5/2021). <i>Advanced Materials Interfaces</i> , 2021, 8, 2170026.	3.7	0